Shenzhen Wisdomshow Technology Co.,ltd

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Semi Automatic BGA Rework Station with High-definition Touchscreen HMI Independent Three-zone Control and ±0.01mm Mounting Accuracy

Our Product Introduction

Basic Information

Brand Name:	Wisdomshow
Certification:	CE
Model Number:	WDS-620
Minimum Order Quantity:	1
Packaging Details:	Wooden Case
Delivery Time:	3-5days
Payment Terms:	TT
Supply Ability:	200

Product Specification

Touch Screen:	High-definition Touchscreen HMI
Min Chip Space:	0.15mm
Heating Body:	Upper/lower Hot Air Heating + Bottom IR Preheating
Power Supply Ac:	Ac 220v ± 10% 50/60hz
Packaging Type:	Wooden Box
Characteristic:	Independent Three-zone Control, Displays 4 Temperature Curves Simultaneously, Stores Multiple User Data Sets, Real-time Curve Analysis; Fan Speed Saved With Temperature Curve; Gear Rack Drives Upper Heating Head For Durability
Dimensions:	L605 × W655 × H710 Mm
Mounting Accuracy:	±0.01mm

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Product Description:

The Semi Automatic BGA Rework Station is a state-of-the-art solution designed for precise and efficient CPU repair and rework tasks. Engineered with advanced technology, this station is ideal for professionals who require high accuracy and reliability in handling delicate electronic components. Its robust design and innovative features make it an indispensable tool in the field of electronics repair, especially for BGA (Ball Grid Array) components.

One of the standout features of this Semi Automatic BGA Rework Station is its three independent heating zones. This configuration allows for precise control over the heating process, ensuring each zone can be adjusted independently according to the specific requirements of the component being worked on. The heating zones contribute significantly to minimizing thermal stress on the CPU and other sensitive parts, thereby enhancing the overall repair quality and reducing the risk of damage.

The heating body of the station incorporates a combination of upper and lower hot air heating along with bottom infrared (IR) preheating. This tri-mode heating approach ensures uniform and thorough heat distribution across the entire component. The upper and lower hot air heating system provides direct and controlled airflow to the component's surface, while the bottom IR preheating gently warms the substrate from underneath. This balanced heating method is crucial for achieving optimal soldering results and preventing warping or cracking during the repair process.

Precision is paramount in CPU repair, and this BGA Rework Station excels with its exceptional mounting accuracy of ±0.01mm. Such a high degree of accuracy is essential when realigning and placing BGA components to avoid misalignment issues that could lead to poor electrical connections or component failure. The station's optical alignment system further enhances this precision by providing real-time visual feedback and assisting the technician in accurately positioning the component. This system reduces the likelihood of errors and improves the efficiency of the repair process.

User experience is greatly enhanced by the station's high-definition touchscreen HMI (Human-Machine Interface). The touchscreen interface is intuitive and responsive, allowing operators to easily navigate through various settings, monitor temperature profiles, and control the heating zones with precision. The clear display and user-friendly controls reduce the learning curve and increase productivity, making it suitable for both experienced technicians and those new to BGA rework.

In terms of physical specifications, the Semi Automatic BGA Rework Station measures L605 × W655 × H710 mm, providing a compact yet spacious platform that fits comfortably in most workspaces. Its dimensions are optimized to accommodate a wide range of PCB sizes while maintaining stability and ease of access to all functional areas. The sturdy construction ensures durability and long-term use, making it a reliable investment for repair shops and manufacturing environments.

Designed for semi-automatic operation, this BGA Rework Station strikes the perfect balance between manual control and automation. It allows technicians to retain control over critical aspects of the repair while benefiting from automated features that enhance consistency and reduce manual labor. This semi automatic functionality is particularly advantageous in CPU repair, where delicate handling and precision are mandatory.

Overall, the Semi Automatic BGA Rework Station is a highly capable and versatile tool tailored to meet the demands of modern electronic repair. Its three independent heating zones, combined heating body with upper/lower hot air and bottom IR preheating, exceptional mounting accuracy, advanced optical alignment system, and user-friendly touchscreen interface make it a top choice for professionals engaged in CPU repair and BGA rework. Whether in a repair workshop or a small-scale production setting, this station delivers outstanding performance, reliability, and precision.

Features:

Product Name: Semi Automatic BGA Rework Station
Machine Weight: Net Weight 55 Kg
Packaging Type: Wooden Box
Heating Zones: Three Independent Heating Zones
Heating Body: Upper/lower Hot Air Heating + Bottom IR Preheating
Power Supply AC: AC 220v ± 10%, 50/60Hz
Advanced hot air heating for precise temperature control
Integrated optical alignment system for accurate component placement
Reliable hot air heating ensures uniform heat distribution

Technical Parameters:

Type	BGA Rework Station
Mounting Accuracy	±0.01mm
Machine Weight	Net Weight 55 Kg
Packaging Type	Wooden Box
Working Modes	5 Modes: Disassembly, Soldering, Placement, Semi-automatic, Manual
Heating Zones	Three Independent Heating Zones

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Min Chip Space	0.15mm
Heating Body	Upper/lower Hot Air Heating + Bottom IR Preheating
Temp Seasuring Interface	1 Pc
Characteristic	Independent Three-zone Control, Displays 4 Temperature Curves Simultaneously, Stores Multiple User Data Sets, Real-time Curve Analysis; Fan Speed Saved With Temperature Curve; Gear Rack Drives Upper Heating Head For Durability

Applications:

The Wisdomshow WDS-620 Semi Automatic BGA Rework Station is an advanced and versatile tool designed for precision motherboard repair and component rework. Originating from China and certified with CE, this machine is ideal for electronics professionals who require high accuracy and reliability. With a net weight of 55 Kg and a mounting accuracy of ±0.01mm, the WDS-620 ensures precise handling of delicate components, making it indispensable in scenarios involving complex motherboard repair tasks.

This rework station features an independent three-zone control system that allows operators to manage temperature precisely across different heating zones. Its capability to display four temperature curves simultaneously and store multiple user data sets facilitates real-time curve analysis, optimizing the soldering and desoldering processes. The integration of a fan speed control that is saved with the temperature curve further enhances the efficiency of hot air heating, ensuring uniform heat distribution without damaging sensitive parts.

The WDS-620's optical alignment system significantly improves placement accuracy, which is critical when working with BGA components on motherboards. This feature, combined with the gear rack-driven upper heating head, provides enhanced durability and smooth operation, making the machine suitable for repetitive and demanding rework processes. The semi-automatic and manual working modes, along with the disassembly, soldering, placement, and semi-automatic modes, offer flexibility to technicians, allowing them to adapt the station to various repair scenarios.

Packaged securely in a wooden box, the Wisdomshow WDS-620 ensures safe delivery within 3-5 days, with a minimum order quantity of 1 unit and a supply ability of 200 units. Its payment terms via TT make it convenient for businesses to acquire this efficient BGA rework station. This product is perfectly suited for electronics repair shops, manufacturing lines, and R&D laboratories where precision motherboard repair and component rework are routine tasks.

In summary, the Wisdomshow WDS-620 Semi Automatic BGA Rework Station combines advanced temperature control, precise optical alignment, and durable mechanical design to meet the demanding requirements of modern electronic repair and manufacturing environments. Its diverse working modes and user-friendly interface make it an essential tool for professionals working with high-density circuit boards and BGA components.

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